

In the Specification:

Please amend the paragraph beginning on page 1, line 4, as follows:

~~BACKGROUND OF THE INVENTION~~

Please amend the paragraph beginning on page 1, line 5, as follows:

Technical Field of the Invention

A1
~~The present invention relates to an~~ An additive for a photoresist composition for a resist flow process, and a photoresist composition comprising the same are disclosed. In particular, ~~the present invention relates to~~ a photoresist composition comprising an additive which lowers the glass transition temperature of the photoresist polymer, and a method for forming a contact hole using the same are disclosed.

Please amend the paragraph beginning on page 3, line 2, as follows:

A2
~~The present invention provides an~~ An additive for a photoresist composition for a resist flow process, and a photoresist composition comprising the same are disclosed. In particular, ~~the present invention provides~~ a photoresist composition comprising the additive which lowers the glass transition temperature of the photoresist polymer, thereby improving a flow property of photoresist composition during a resist flow process is disclosed.

Please amend the paragraph beginning on page 3, line 8, as follows:

A3
In one particular aspect, ~~the present invention provides an~~ a disclosed additive of following Formula 1 for the photoresist composition which is used for a resist flow process:

Please amend the paragraph beginning on page 5, line 7, as follows:

A4
~~Another aspect of the present invention provides a~~ A disclosed photoresist composition ~~comprising~~ comprises a photoresist polymer, a photoacid generator, an organic solvent and the additive of Formula 1.

ME

Please amend the paragraph beginning on page 5, line 10, as follows:

~~Another aspect of the present invention provides a~~ A disclosed photoresist composition ~~comprising~~ comprises a photoresist polymer, a photoacid generator, an organic solvent and the additive of Formula 1.

Please amend the paragraph beginning on page 5, line 10, as follows:

AS

The ~~present~~ disclosed photoresist composition comprising the additive of Formula 1 is suitable for the resist flow process. As described above, a photoresist polymer having very high glass transition temperature (T_g) cannot be used for resist flow process since the T_g and decomposition temperature (T_d) have only a slight difference. However, the additive of Formula 1 serves to lower the T_g , thus improving a flow property of the photoresist composition. As a result, the photoresist composition can be suitably employed for the resist flow process.

Please amend the paragraph beginning on page 15, line 19, as follows:

AG

The foregoing discussion ~~of the invention~~ has been presented for purposes of illustration and description. The foregoing is not intended to limit the invention to the form or forms disclosed herein. Although the description of the invention has included description of one or more embodiments and certain variations and modifications, other variations and modifications are within the scope of the invention, *e.g.*, as may be within the skill and knowledge of those in the art, after understanding the present disclosure. It is intended to obtain rights which include alternative embodiments to the extent permitted, including alternate, interchangeable and/or equivalent structures, functions, ranges or steps to those claimed, whether or not such alternate, interchangeable and/or equivalent structures, functions, ranges or steps are disclosed herein, and without intending to publicly dedicate any patentable subject matter.